Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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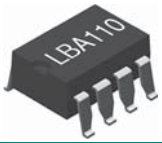
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

IXYS
INTEGRATED CIRCUITS DIVISION



LBA110
Dual Pole OptoMOS® Relay

Parameter	Ratings	Units
Blocking Voltage	350	V_P
Load Current	120	mA_{rms} / mA_{DC}
On-Resistance (max)	35	Ω

Features
- 3750V_{rms} Input/Output Isolation
- 100% Solid State
- Low Drive Power Requirements (TTL/CMOS Compatible)
- Arc-Free With No Snubbing Circuits
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- Machine Insertable, Wave Solderable

Applications
- Telecommunications
  - Telecom Switching
  - Tip/Ring Circuits
  - Modem Switching (Laptop, Notebook, Pocket Size)
  - Hook Switch
  - Dial Pulsing
  - Ground Start
  - Ringing Injection
- Instrumentation
  - Multiplexers
  - Data Acquisition
  - Electronic Switching
  - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description
LBA110 comprises two independent 350V, 120mA, 35Ω solid state relays: one single-pole, normally open (1-Form-A) relay and one single-pole, normally closed (1-Form-B) relay.

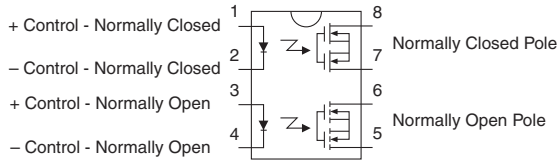
LBA110 is designed to provide an ideal solution where a complementary Form-A/Form-B relay pair is required.

Approvals
- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component
  TUV Certificate B 09 07 49410 004

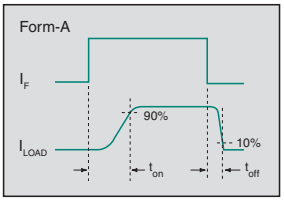
Ordering Information

Part #	Description
LBA110	8-Pin DIP (50/Tube)
LBA110S	8-Pin Surface Mount (50/Tube)
LBA110STR	8-Pin Surface Mount (1,000/Reel)
LBA110P	8-Pin Flat Pack (50/Tube)
LBA110PTR	8-Pin Flat Pack (1,000/Reel)

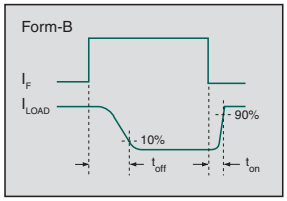
Pin Configuration



Switching Characteristics of Normally Open Devices



Switching Characteristics of Normally Closed Devices



Absolute Maximum Ratings @ 25ºC

Parameter	Ratings	Units
Blocking Voltage	350	V_P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation [1]	150	mW
Total Power Dissipation [2]	800	mW
Isolation Voltage, Input to Output	3750	V_{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

[1] Derate linearly 1.33 mW / ºC
[2] Derate linearly 6.67 mW / ºC

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

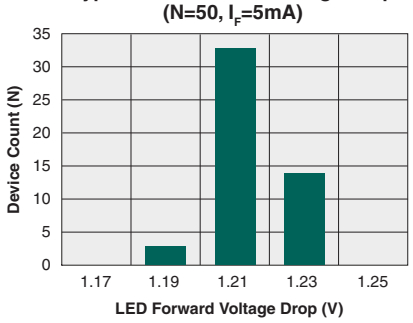
Electrical Characteristics @ 25ºC

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current						
Continuous [1]	-	I_L	-	-	120	mA_{rms} / mA_{DC}
Peak	t = 10ms	I_{LPK}	-	-	±350	mA_P
On-resistance	I_L=120mA	R_{ON}	-	25	35	Ω
Off-State Leakage Current	V_L=350V_P	I_{LEAK}	-	-	1	µA
Switching Speeds						
Turn-On	I_F=5mA, V_L=10V	t_{on}	-	-	3	ms
Turn-Off		t_{off}	-	-	3	
Output Capacitance	V_L=50V, f=1MHz	C_{OUT}	-	25	-	pF
Input Characteristics						
Input Control Current to Activate	I_L=120mA	I_F	-	-	2	mA
Input Control Current to Deactivate	-	I_F	0.4	0.7	-	mA
Input Voltage Drop	I_F=5mA	V_F	0.9	1.2	1.4	V
Reverse Input Current	V_R=5V	I_R	-	-	10	µA
Common Characteristics						
Input to Output Capacitance	-	$C_{I/O}$	-	3	-	pF

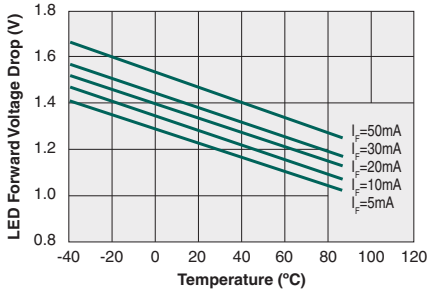
[1] If both poles operate the load current must be derated so as not to exceed the package power dissipation value.

Form-A/Form-B PERFORMANCE DATA @25ºC (Unless Otherwise Noted)*

Typical LED Forward Voltage Drop (N=50, I_F=5mA)

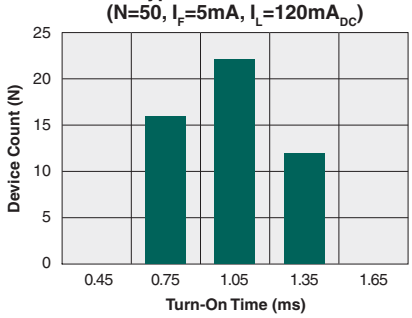


Typical LED Forward Voltage Drop vs. Temperature

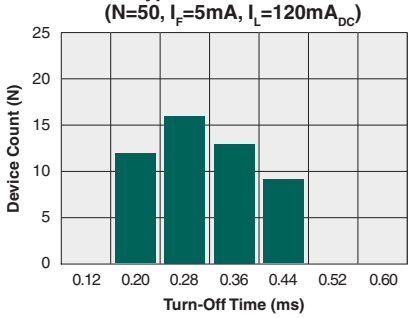


Form-A PERFORMANCE DATA @25ºC (Unless Otherwise Noted)*

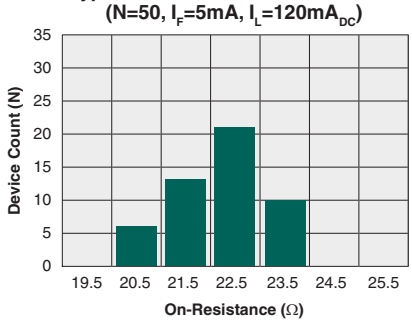
Form-A Typical Turn-On Time (N=50, I_F=5mA, I_L=120mA$_{DC}$)



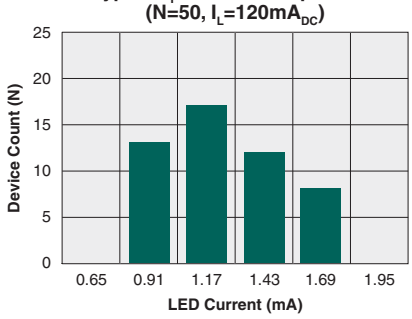
Form-A Typical Turn-Off Time (N=50, I_F=5mA, I_L=120mA$_{DC}$)



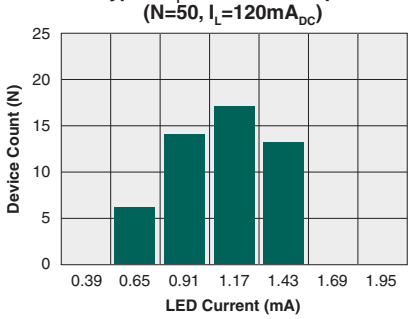
Form-A Typical On-Resistance Distribution (N=50, I_F=5mA, I_L=120mA$_{DC}$)



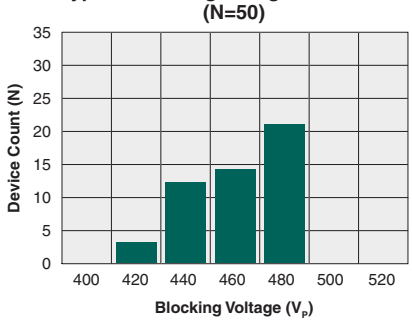
Form-A Typical I_F for Switch Operation (N=50, I_L=120mA$_{DC}$)



Form-A Typical I_F for Switch Dropout (N=50, I_L=120mA$_{DC}$)



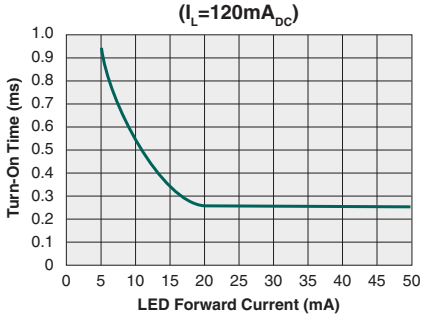
Form-A Typical Blocking Voltage Distribution (N=50)



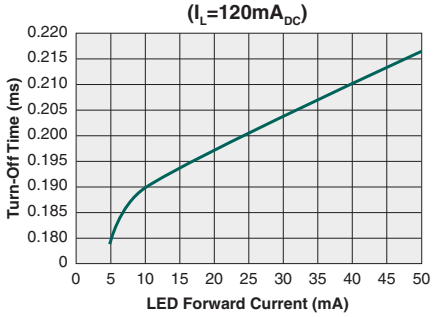
*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Form-A PERFORMANCE DATA @25°C (Unless Otherwise Noted)*

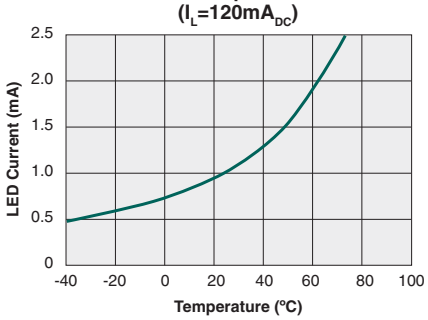
Form-A
Typical Turn-On Time
vs. LED Forward Current
(I_L=120mA$_{DC}$)



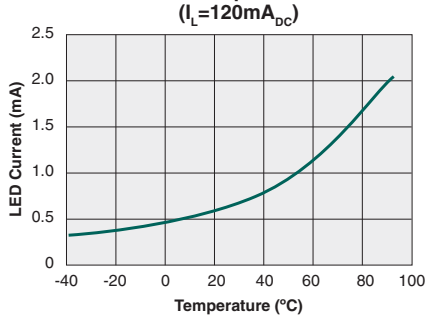
Form-A
Typical Turn-Off Time
vs. LED Forward Current
(I_L=120mA$_{DC}$)



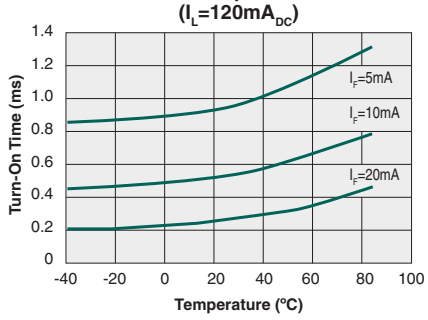
Form-A
Typical I_F for Switch Operation
vs. Temperature
(I_L=120mA$_{DC}$)



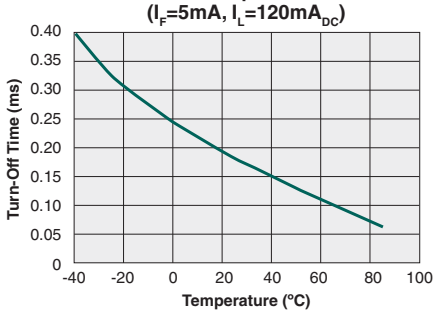
Form-A
Typical I_F for Switch Dropout
vs. Temperature
(I_L=120mA$_{DC}$)



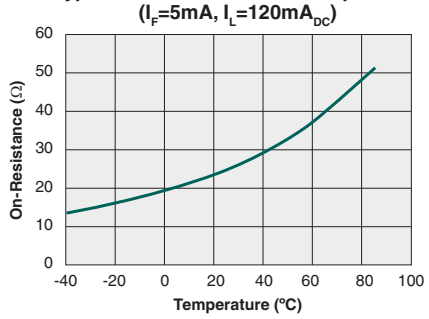
Form-A
Typical Turn-On Time
vs. Temperature
(I_L=120mA$_{DC}$)



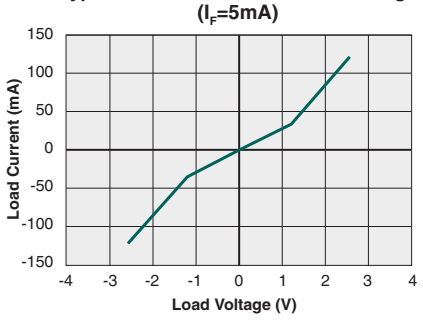
Form-A
Typical Turn-Off Time
vs. Temperature
(I_F=5mA, I_L=120mA$_{DC}$)



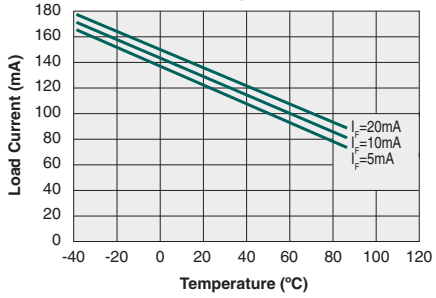
Form-A
Typical On-Resistance vs. Temperature
(I_F=5mA, I_L=120mA$_{DC}$)



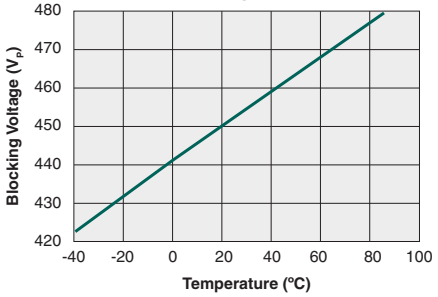
Form-A
Typical Load Current vs. Load Voltage
(I_F=5mA)



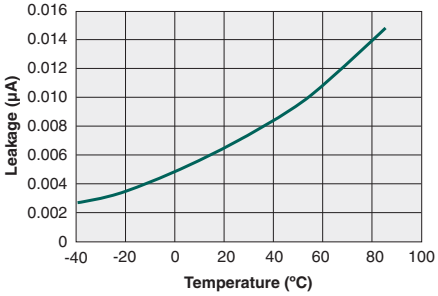
Form-A
Maximum Load Current
vs. Temperature



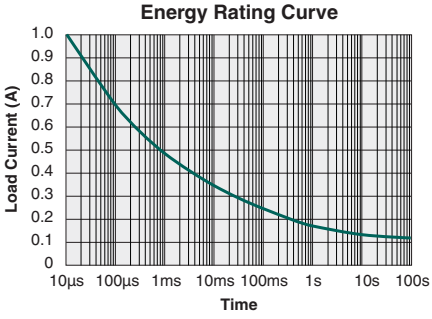
Form-A
Typical Blocking Voltage
vs. Temperature



Form-A
Typical Leakage vs. Temperature
Measured Across Pins 5&6



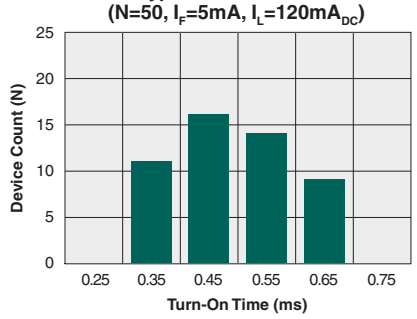
Energy Rating Curve



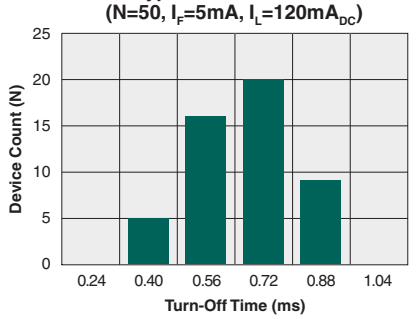
*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Form-B PERFORMANCE DATA @25°C (Unless Otherwise Noted)*

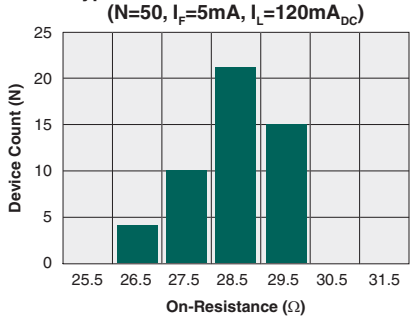
Form-B
Typical Turn-On Time
(N=50, I_F=5mA, I_L=120mA$_{DC}$)



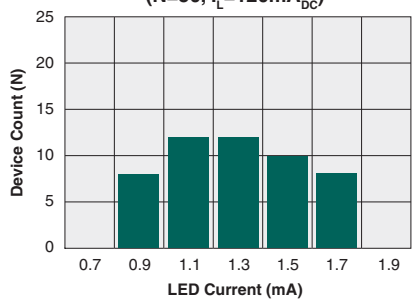
Form-B
Typical Turn-Off Time
(N=50, I_F=5mA, I_L=120mA$_{DC}$)



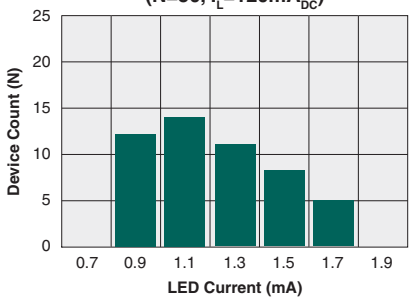
Form-B
Typical On-Resistance Distribution
(N=50, I_F=5mA, I_L=120mA$_{DC}$)



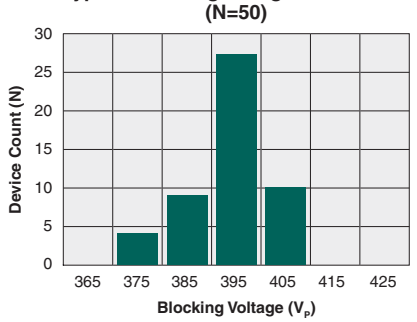
Form-B
Typical I_F for Switch Operation
(N=50, I_L=120mA$_{DC}$)



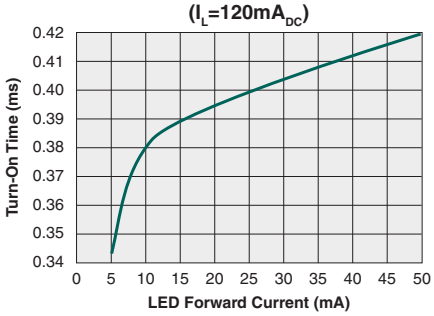
Form-B
Typical I_F for Switch Dropout
(N=50, I_L=120mA$_{DC}$)



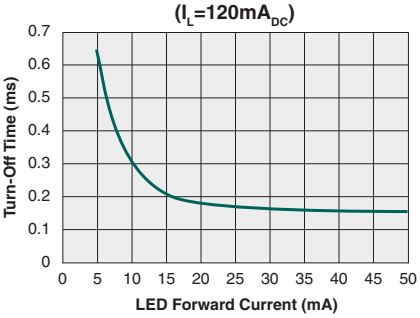
Form-B
Typical Blocking Voltage Distribution
(N=50)



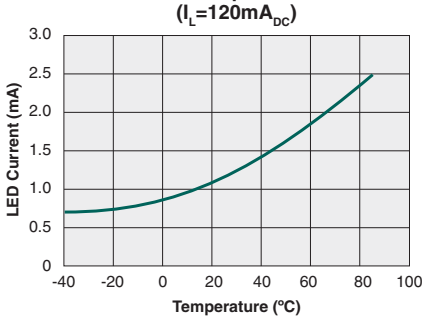
Form-B
Typical Turn-On Time
vs. LED Forward Current
(I_L=120mA$_{DC}$)



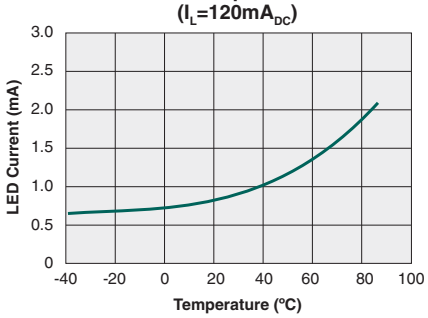
Form-B
Typical Turn-Off Time
vs. LED Forward Current
(I_L=120mA$_{DC}$)



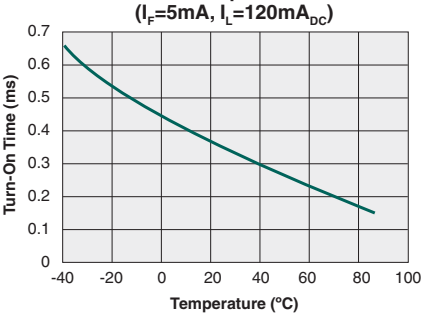
Form-B
Typical I_F for Switch Operation
vs. Temperature
(I_L=120mA$_{DC}$)



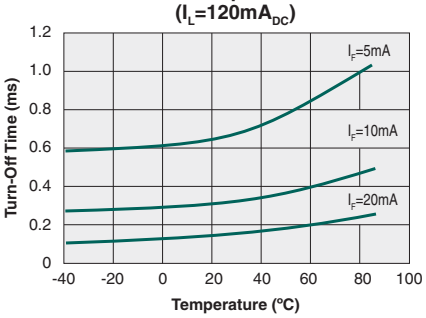
Form-B
Typical I_F for Switch Dropout
vs. Temperature
(I_L=120mA$_{DC}$)



Form-B
Typical Turn-On Time
vs. Temperature
(I_F=5mA, I_L=120mA$_{DC}$)



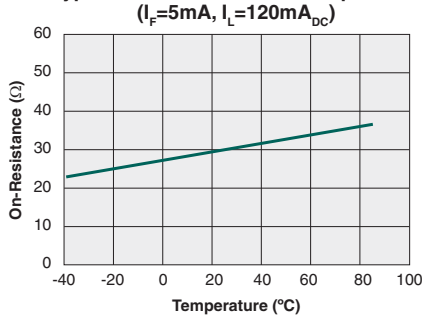
Form-B
Typical Turn-Off Time
vs. Temperature
(I_L=120mA$_{DC}$)



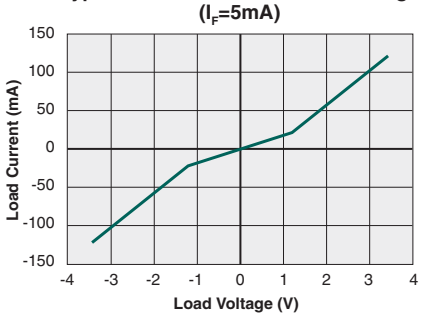
*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Form-B PERFORMANCE DATA @25ºC (Unless Otherwise Noted)*

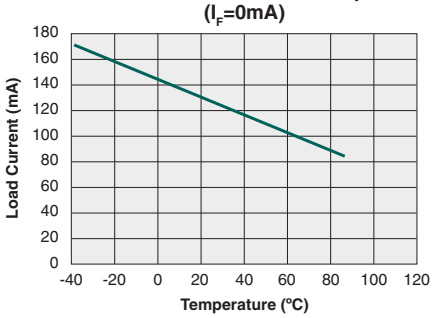
Form-B
Typical On-Resistance vs. Temperature
(I_F=5mA, I_L=120mA$_{DC}$)



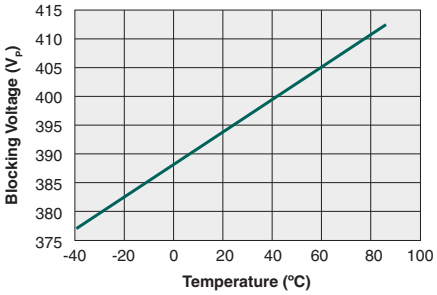
Form-B
Typical Load Current vs. Load Voltage
(I_F=5mA)



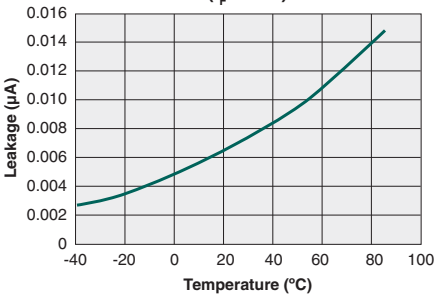
Form-B
Maximum Load Current vs. Temperature
(I_F=0mA)



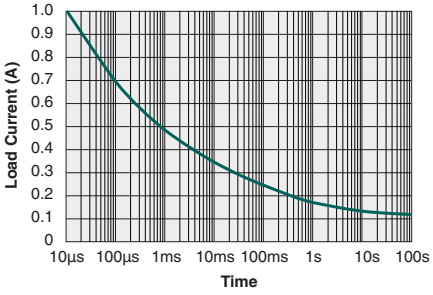
Form-B
Typical Blocking Voltage
vs. Temperature



Form-B
Typical Leakage vs. Temperature
Measured Across Pins 5&6
(I_F=5mA)



Energy Rating Curve



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
LBA110 / LBA110S / LBA110P	MSL 1

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

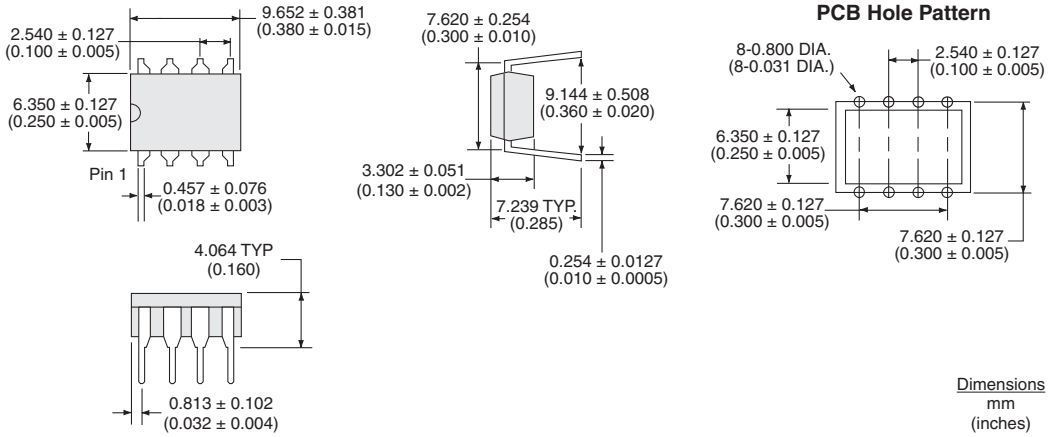
Device	Maximum Temperature x Time
LBA110 / LBA110S	250°C for 30 seconds
LBA110P	260°C for 30 seconds

Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

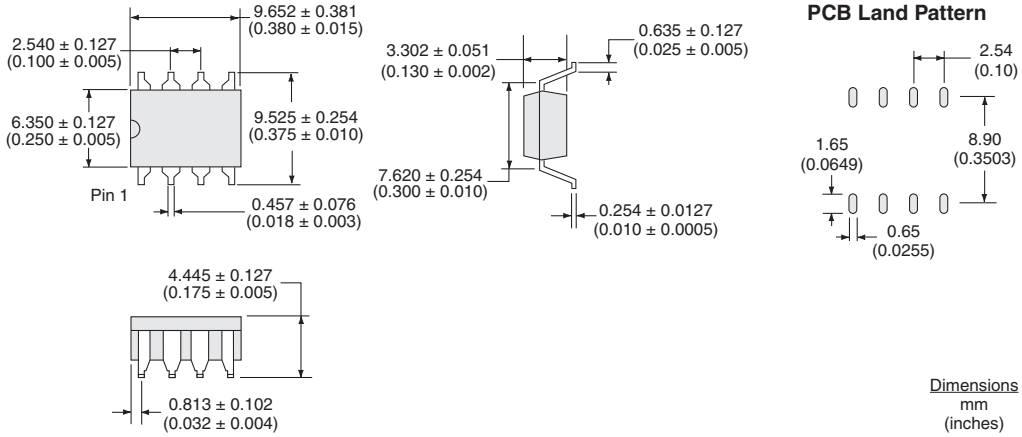
MECHANICAL DIMENSIONS

LBA110



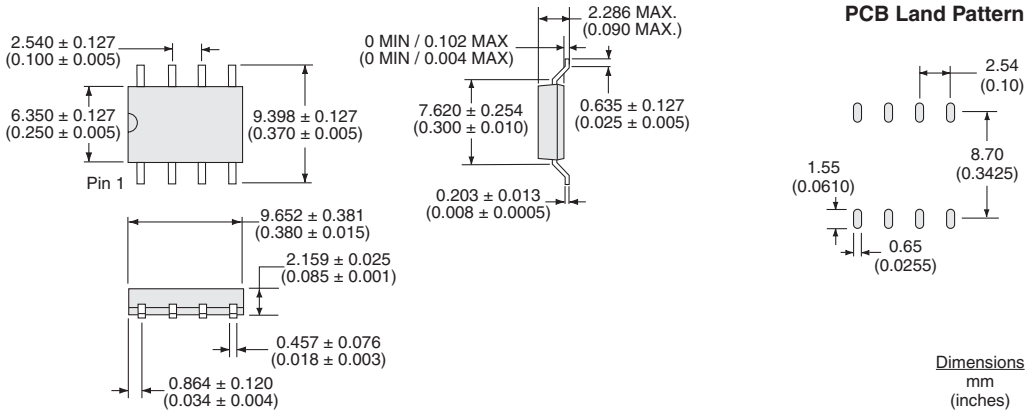
Dimensions
mm
(inches)

LBA110S



Dimensions
mm
(inches)

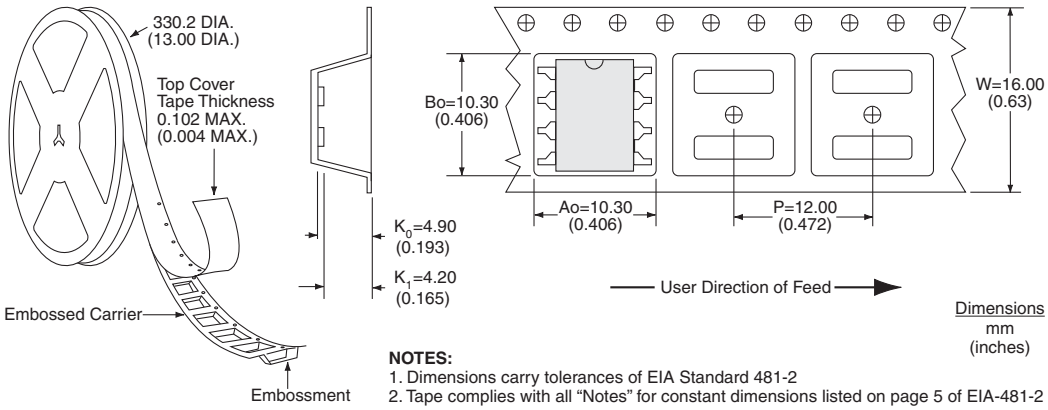
LBA110P



Dimensions
mm
(inches)

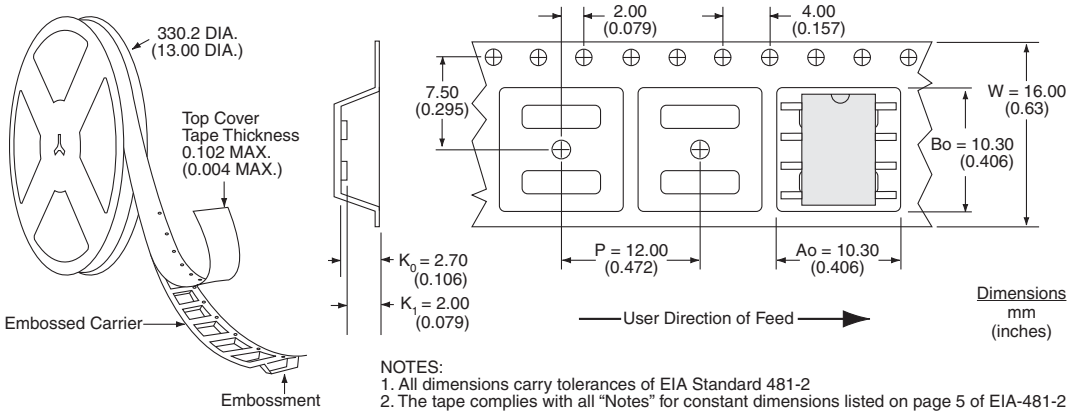
MECHANICAL DIMENSIONS

LBA110STR Tape & Reel



NOTES:
1. Dimensions carry tolerances of EIA Standard 481-2
2. Tape complies with all "Notes" for constant dimensions listed on page 5 of EIA-481-2

LBA110PTR Tape & Reel



NOTES:
1. All dimensions carry tolerances of EIA Standard 481-2
2. The tape complies with all "Notes" for constant dimensions listed on page 5 of EIA-481-2

For additional information please visit our website at: www.ixysic.com

Specification: DS-LBA110-R09

12/22/2012